

Particle Contamination in EUVL: Estimations on the Critical Particle Sizes

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Motivation

Image Placement Error:

$$\text{IPE} \approx \text{OPD}/40 + \text{IPD}/4$$

→ what particle sizes are allowable?

Plate Model

Analytical models in the literature are based on

- Plate bending

$$\text{OPD} = -\frac{h}{a^4}r^4 + \frac{4h}{a^2}r^2 \ln \frac{r}{a} + h, \quad a^4 = \frac{64hD}{p}$$

$$\text{IPD} = -\frac{t_R}{2} \frac{\partial}{\partial r} \text{OPD}$$

- Nano-indentation of semi-infinite half-space
- Cylindrical particle shapes

We extend the theory:

- General material laws (e.g. Romberg-Osgood type constitutive law)
- Frictional contact
- Gap dependant electro-static pressure $p(w)$

$$\text{OPD} = c_1 J_0(\alpha r) + c_2 I_0(\alpha r) + c_3 Y_0(\alpha r) + c_4 K_0(\alpha r) + \frac{\delta_d}{2k_d}, \quad \alpha = \left(\frac{2k_d p_0}{D \delta_d} \right)^{1/4}$$

- Analytical solution for spherical particle shape

Pros & Cons:

- Simple closed form estimate
- Neglects 'plate shearing'
- Neglects 'feature transfer' of the mask-indentation to the front-side

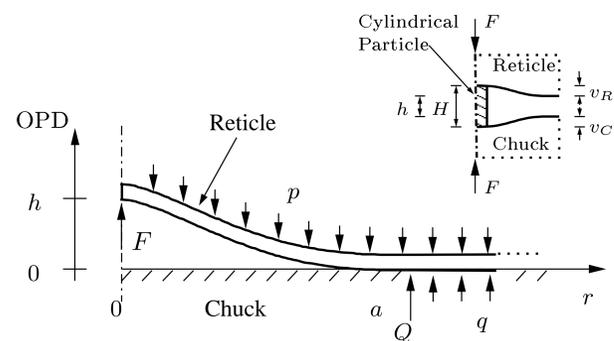


Figure 1: Schematic of the plate model.

Hankel Model

We consider a new analytical approach to model the 'plate shearing' and 'feature transfer'-effect.

- Elasticity solution

$$\text{OPD} = \int_0^\infty \xi \left(\frac{d^2 G}{dz^2} - \frac{\lambda + 2\mu}{\mu} \xi^2 G \right) J_0(\xi r) d\xi,$$

$$\text{IPD} = \int_0^\infty \frac{\lambda + \mu}{\mu} \xi^2 \frac{dG}{dz} J_1(\xi r) d\xi$$

where

$$G(\xi, z) = p(\xi) \Phi(\xi, z)$$

- Hankel transform of stress boundary condition

$$p(\xi) = \int_0^\infty p(r) J_0(\xi r) r dr$$

Pros & Cons:

- Exact 3D elasticity solution
- 'Con': Expensive numerical integration (but cheaper than FEM, still working on adaptive numerical integration schemes)

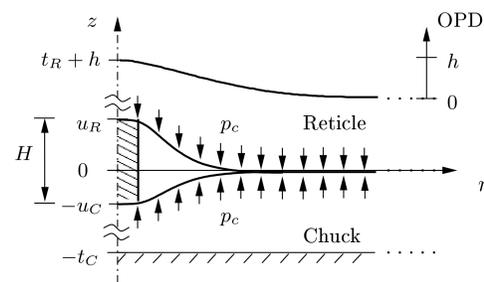


Figure 2: Schematic of the Hankel model.

FE Model

- Current finite element models in the literature use de-coupled global and local models ('feature transfer'-effect neglected)
- We consider a recursive mesh refinement to simulate the fully coupled problem of three bodies in contact

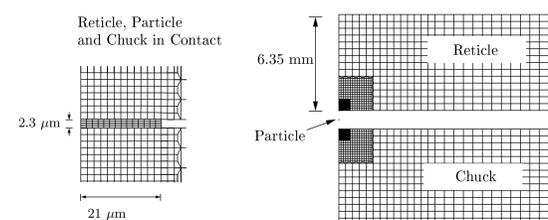


Figure 3: Recursive finite element mesh refinement.

Benchmark Example

Comparing the models for a numerical example:

ULE Reticle	$E_R = 67.6 \text{ GPa}, \nu_R = 0.17$
AlOxide Particle	$E_P = 406 \text{ GPa}, \nu_P = 0.2$
Ceramic Chuck	$E_C = 380 \text{ GPa}, \nu_C = 0.2$

- We observe higher OPD response in the Hankel- and Finite Element Models:

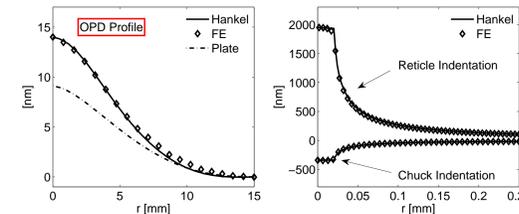


Figure 4: Example OPD profiles for different models at 15 kPa chucking stage.

- All models are close in their IPD-predictions:

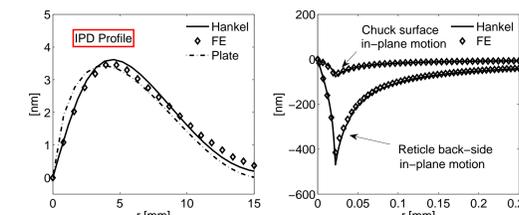


Figure 5: Example IPD profiles for different models at 15 kPa chucking stage.

- Comparing the models for various chucking pressures:

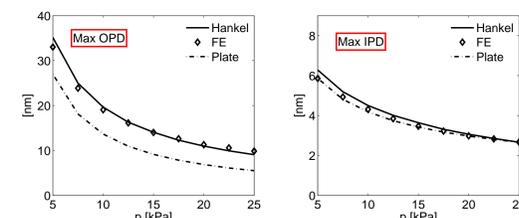


Figure 6: Example maximum OPD/IPD for various pressures.

Example Result

The Hankel- or coupled Finite Element Model is needed to account for the 'feature transfer'-effect to give the correct OPD response.

Critical Particle Sizes

Given an image placement error budget, critical particle sizes are estimated for cylindrical particles and a ULE glass reticle:

- IPD has most contribution to the IPE.
- Softer materials will relax the bounds on the critical particle sizes.

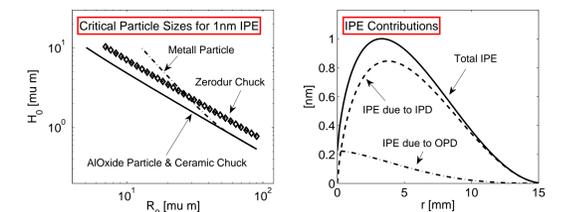


Figure 7: Left: Critical particle sizes for various material combinations at 15 kPa chucking stage. Right: Contributions to the Image Placement Error (IPE) due to the In-plane motion (IPD) and Out-of-plane deformation (OPD).

Result

Given a 1 nm IPE budget, we find critical particle size bounds at 15 kPa chucking stage:

- Cylindrical particles of 1 μm height require radii of less than 47 μm .
- Cylindrical particles of 5 μm height require radii of less than 9 μm .

Secondary Effects

- CrN-layer on reticle back-side → increases OPD/IPD
- Gap dependant electrostatic pressure model → required only for very thin chuck-dielectric
- Frictional contact → increases OPD/IPD
- Chuck pins → decrease OPD/IPD.

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